

<b>ENGINEERING</b>  <b>DEPT.</b>	<b>PRODUCT SPECIFICATION</b>  <b>For Pitch 1.27mm(.050") Pin Header of System CH06</b>	<b>SPEC.NO.: SPCH561</b>  <b>PAGE: 1/3</b>
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1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and appliance
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES No. : **CH06 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

(P.C. Board on which the Pin Header are installed), 1.6 mm (.063")



REVIEWED : Eisley APPROVED : Eisley VERIFIED : Hank .

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**7. ELECTRICAL PERFORMANCE:**

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1.5A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 600 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

**8. MECHANICAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT		
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 0.50 Kgf		
8.2	Mating & Un-mating force	Insert and withdraw connector at speed of 25 ± 3 mm per minute	Mating (Max.)	Unmating (Min.)	
			6P	3.0 Kgf	0.3 Kgf
			14P	4.0 Kgf	0.8 Kgf
			26P	5.0 Kgf	1.5 Kgf
8.3	Locking force	While withdrawing plug & receptacle without terminal at speed 25±3 mm per minute	More than 1.0 Kgf		

**9. ENVIRONMENTAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Lead-Free Process for SMT Type: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	Refer Reflow temperature profile	No damage
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	40± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3

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ITEM	TEST CONDITION	REQUIREMENT
9.5	Temperature cycling One cycle consists of : (1)-55 <sup>+0</sup> / <sub>-3</sub> °C , 30 min. (2)Room temp. 10-15 min. (3) 85 <sup>+3</sup> / <sub>-0</sub> °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.6	Salt spray Temperature: 35± 3°C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C

11. Recommended IR Reflow Temperature Profile:

